

Amendments to the Claims: This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. (Currently Amended) A high frequency laminated device comprising:

a laminated body including

a first sheet having a relative permeability larger than 1,

a second sheet having a relative permeability larger than 1 ~~[[on]]~~over a first surface of said first sheet, and

a third sheet ~~provided over a second surface of~~under said first sheet;

a first inductor pattern for forming a first inductor and provided between said first and second sheets; and

first and second capacitor patterns forming a capacitor and ~~opposed to each other about~~situated between said first sheet and said third sheet therebetween.

2. (Original) The high frequency laminated device of claim 1, wherein said third sheet comprises a dielectric sheet.

3. (Currently Amended) The high frequency laminated device of claim 2, wherein said first and third sheets are stacked and sintered after said first capacitor pattern is printed ~~at an interface between said first and third sheets.~~

4. (Original) The high frequency laminated device of claim 1, further comprising a via-conductor formed in said first sheet, for electrically connecting said first inductor pattern and said first capacitor pattern.

5. (Original) The high frequency laminated device of claim 1, further comprising a circuit element mounted on a surface of said laminated body and connected to at least one of said first inductor and said capacitor.

6. (Original) The high frequency laminated device of claim 1, further comprising a second inductor pattern forming a second inductor provided between said first and second sheets.